

SFM21-BS THRU SFM28-BS

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SFM21-BS THRU SFM28-BS

2.0A Surface Mount Super Fast Rectifiers 50V-600V

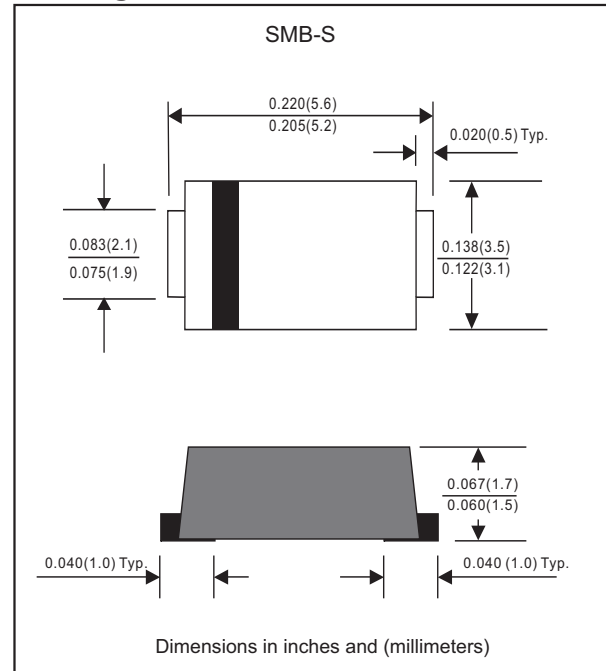
Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance
- Low profile surface mounted application in order to optimize board space
- High current capability
- Superfast recovery tim for switching mode application
- High surge current capability
- Glass passivated chip junction
- Lead-free parts meet RoHS requirements
- Suffix "-H" indicates Halogen free parts, ex. SFM21-BS-H

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, SMB-S
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.072 gram

Package outline



Maximum ratings (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	SFM21-BS	SFM22-BS	SFM23-BS	SFM24-BS	SFM25-BS	SFM26-BS	SFM27-BS	SFM28-BS	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	150	200	300	400	500	600	V
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	350	420	V
Maximum continuous reverse voltage	V_R	50	100	150	200	300	400	500	600	V
Maximum average forward rectified current	I_o	2.0								A
Non-repetitive peak forward surge current 8.3ms single half sine-wave	I_{FSM}	50								A
Typical junction capacitance (Note 1)	C_J	25								pF
Operating junction temperature range	T_J	-55 to +150								$^{\circ}\text{C}$
Storage temperature range	T_{STG}	-65 to +175								$^{\circ}\text{C}$

Electrical characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	SFM21-BS	SFM22-BS	SFM23-BS	SFM24-BS	SFM25-BS	SFM26-BS	SFM27-BS	SFM28-BS	UNIT
Maximum instantaneous forward voltage at $I_f=2.0A$	V_f	0.95				1.25		1.70		V
Maximum reverse leakage current $T_J=25^{\circ}\text{C}$ at rated V_R $T_J=125^{\circ}\text{C}$	I_r					5.0 100				μA μA
Maximum reverse recovery time (Note 2)	t_{rr}					35				ns

Thermal characteristics

PARAMETER	SYMBOLS	SFM21-BS	SFM22-BS	SFM23-BS	SFM24-BS	SFM25-BS	SFM26-BS	SFM27-BS	SFM28-BS	UNIT
Typical thermal resistance junction to ambient (3)	$R_{\theta JA}$					37				$^{\circ}\text{C}/\text{W}$
Typical thermal resistance junction to case(3)	$R_{\theta JC}$					22				$^{\circ}\text{C}/\text{W}$

Notes 1: Measured at 1 MHz and applied reverse voltage of 4.0 VDC

2: Measured with $I_f = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$

3: Mounted on FR-4 PCB Copper, minimum recommended pad layout

Rating and characteristic curves (SFM21-BS THRU SFM28-BS)

FIG.1-TYPICAL FORWARD CHARACTERISTICS

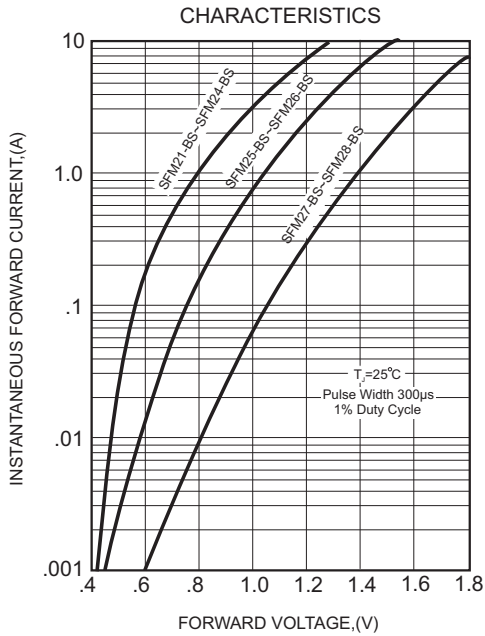


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

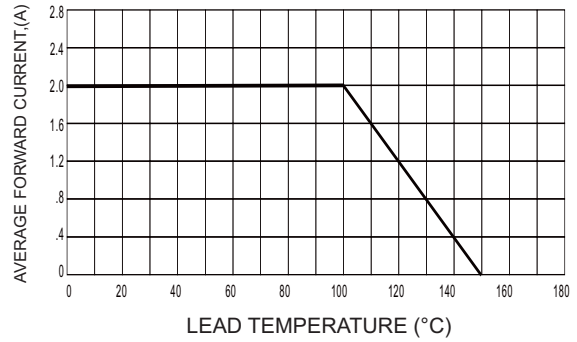


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

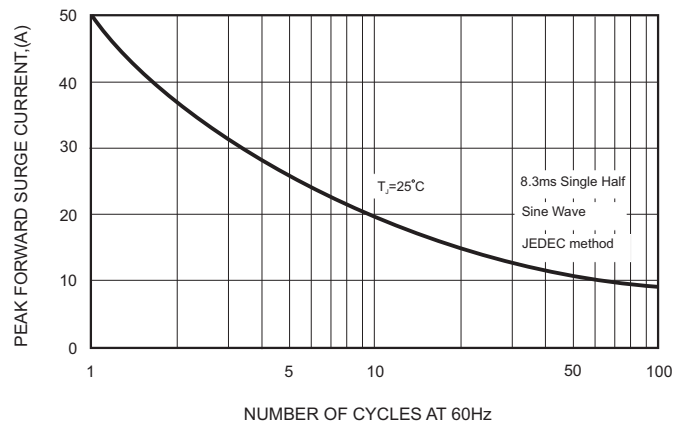
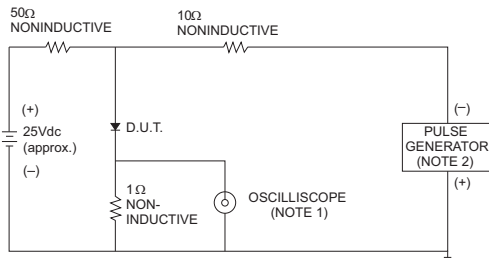


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



- NOTES: 1. Rise Time = 7ns max., Input Impedance = 1 megohm, 22pF.
2. Rise Time = 10ns max., Source Impedance = 50 ohms.

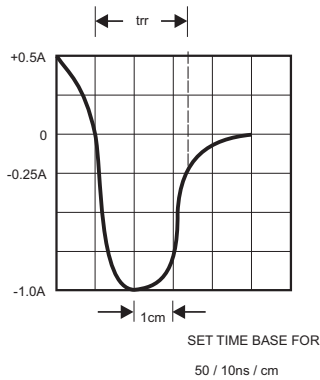
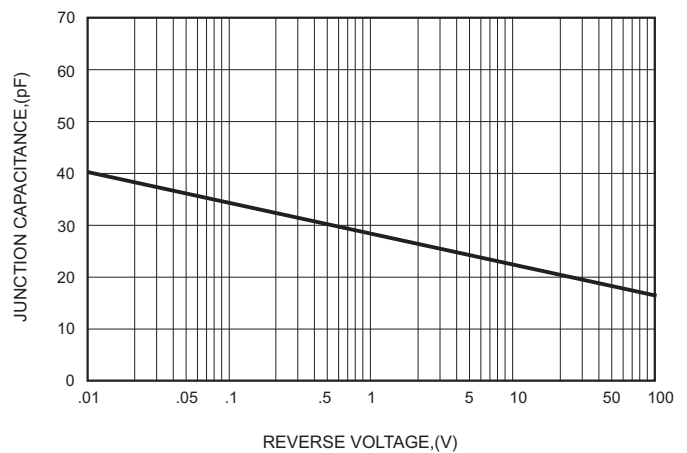




FIG.5-TYPICAL JUNCTION CAPACITANCE



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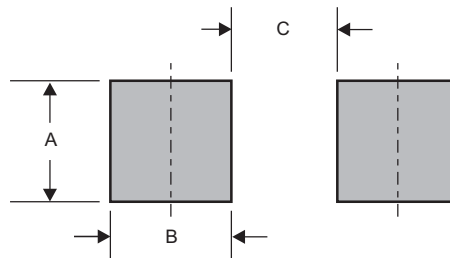
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
SFM21-BS	S21
SFM22-BS	S22
SFM23-BS	S23
SFM24-BS	S24
SFM25-BS	S25
SFM26-BS	S26
SFM27-BS	S27
SFM28-BS	S28

Suggested solder pad layout

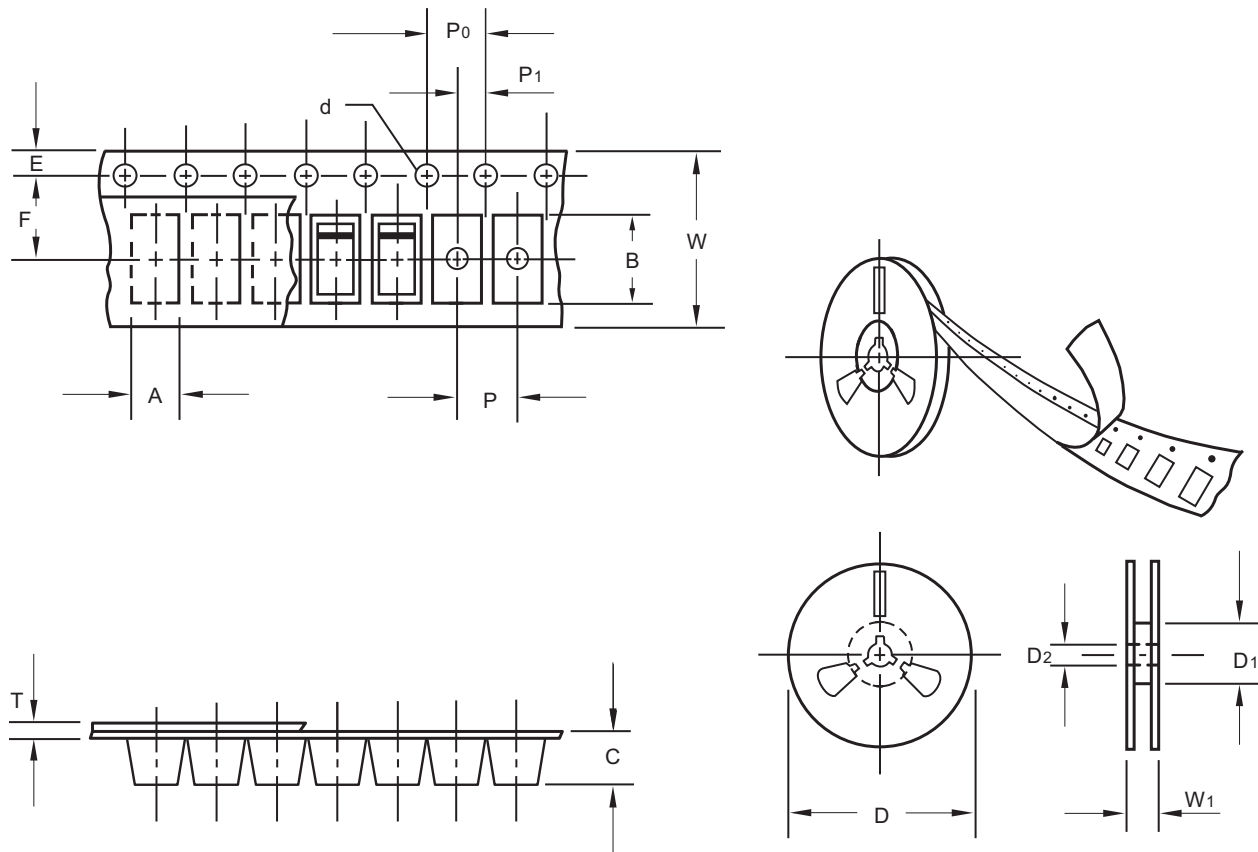


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMB-S	0.078 (2.00)	0.059 (1.50)	0.110 (2.80)

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Packing information



unit:mm

Item	Symbol	Tolerance	SMB-S
Carrier width	A	0.1	3.81
Carrier length	B	0.1	5.74
Carrier depth	C	0.1	2.24
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D1	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	62.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	12.00
Reel width	W1	1.0	18.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

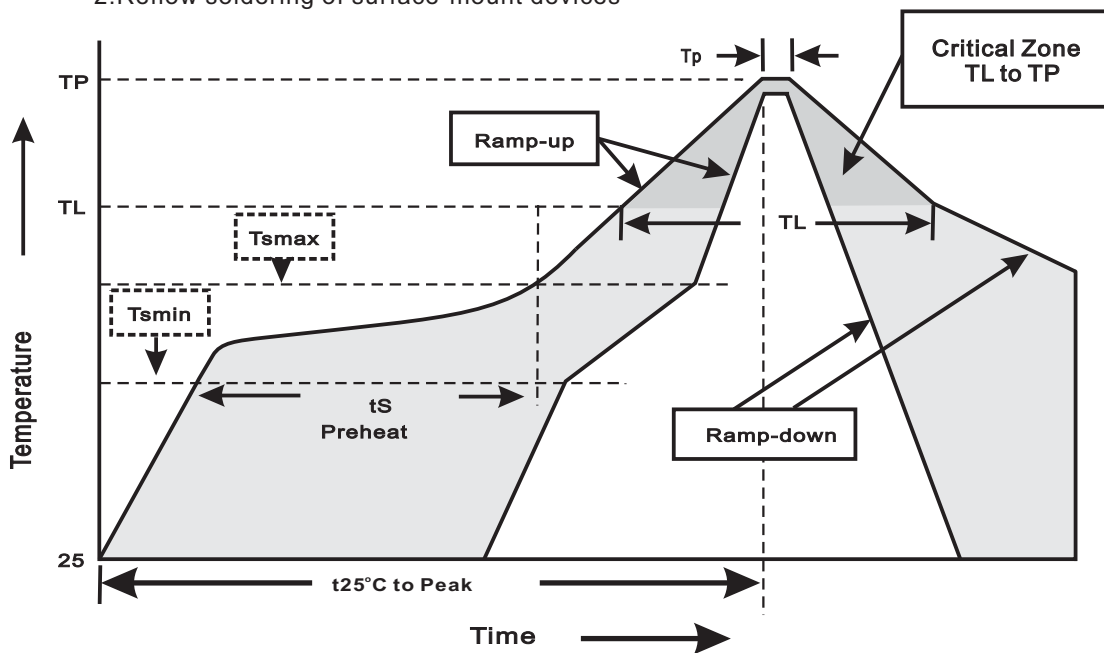
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Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMB-S	13"	4,000	8.0	8,000	335*335*38	330	350*330*360	64,000	13.0

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at 260±5°C for 10±2sec.	MIL-STD-750D METHOD-2031
2. Solderability	at 245±5°C for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R=80\%$ rate at $T_J=150^\circ\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A=25^\circ\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^\circ\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	15P _{SIG} at $T_A=121^\circ\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	-55°C to +125°C dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Forward Surge	8.3ms single half sine-wave , one surge.	MIL-STD-750D METHOD-4066-2
9. Humidity	at $T_A=85^\circ\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
10. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031